



# SGM2529

## 5A, 5V Electronic Fuse (eFuse) with Thermal Shutdown

### GENERAL DESCRIPTION

The SGM2529 is a compact electronic fuse (eFuse) with a complete set of protection functions. The SGM2529 provides excellent accuracy, making it very suitable for many system protection applications.

It provides accurate over-voltage (OV) and under-voltage lockout (UVLO) protections, which ensure tight supervision of bus voltages and eliminate the need for supervisor circuits. The over-voltage (OV) protection will clamp the eFuse output at a fixed level during input voltage surges. During the input voltage transient, the internal FET remains on, which allows the load to continue to operate. If the transient duration remains long, the accumulated heat will cause the eFuse thermal shutdown. Once in thermal shutdown, latch-off and auto-retry thermal options are available.

The SGM2529 is available in a Green TDFN-3×3-10L package.

### FEATURES

- **5V Electronic Fuse with Surge up to 30V**
- **Extremely Low  $R_{DS(ON)}$  for the Integrated Protection Switch: 26mΩ (TYP)**
- **3-State ENABLE/FAULT Pin, Bidirectional Interface**
- **Programmable Soft-Start Time**
- **Programmable Current Limit up to 5A**
- **Thermal Shutdown Options:**
  - **SGM2529A: Thermal Latch-Off with  $V_{CLAMP}$**
  - **SGM2529B: Thermal Auto-Retry with  $V_{CLAMP}$**
  - **SGM2529C: Thermal Latch-Off without  $V_{CLAMP}$**
- **Fault Output for Thermal Shutdown**
- **Accurate Under-Voltage Lockout**
- **Accurate Over-Voltage Clamp (SGM2529A and SGM2529B)**
- **Available in a Green TDFN-3×3-10L Package**

### APPLICATIONS

Hard Drives  
PCIE SSD  
Motherboard Power Management

## PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM2529A	TDFN-3x3-10L	-40°C to +125°C	SGM2529AXTD10G/TR	SGM 2529AD XXXXX	Tape and Reel, 4000
SGM2529B	TDFN-3x3-10L	-40°C to +125°C	SGM2529BXTD10G/TR	SGM 2529BD XXXXX	Tape and Reel, 4000
SGM2529C	TDFN-3x3-10L	-40°C to +125°C	SGM2529CXTD10G/TR	SGM 2529CD XXXXX	Tape and Reel, 4000

## MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.

**XXXXX**



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

## ABSOLUTE MAXIMUM RATINGS

Operating Input Voltage Range ( $V_{CC}$  to GND)<sup>(1)</sup>

Steady-State .....	-0.3V to 18V
Transient (100ms) .....	-0.6V to 25V
$V_{CC}$ , SOURCE, $I_{LIMIT}$ to GND.....	-0.3V to 25V
$dV/dt$ , ENABLE/FAULT to GND .....	-0.3V to 5.5V
Package Thermal Resistance	
TDFN-3x3-10L, $\theta_{JA}$ .....	90°C/W
TDFN-3x3-10L, $\theta_{JB}$ .....	54°C/W
TDFN-3x3-10L, $\theta_{JC}$ .....	52°C/W
Junction Temperature .....	+150°C
Storage Temperature Range .....	-65°C to +150°C
Lead Temperature (Soldering, 10s) .....	+260°C
ESD Susceptibility	
HBM.....	2000V
CDM .....	1000V

NOTE: 1. Negative voltage will not damage device provided that the power dissipation is limited to the rated allowable power for the package.

## RECOMMENDED OPERATING CONDITIONS

Operating Junction Temperature Range ..... -40°C to +125°C

## OVERSTRESS CAUTION

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

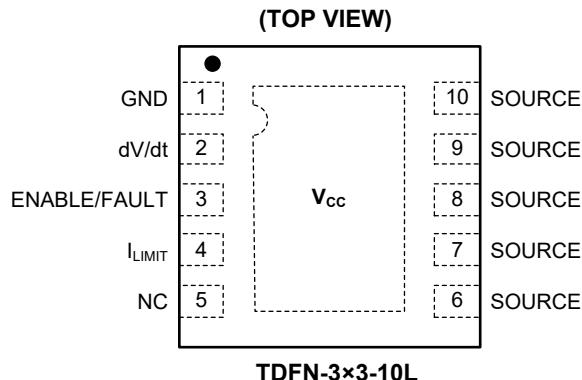
## ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

## DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

## PIN CONFIGURATION



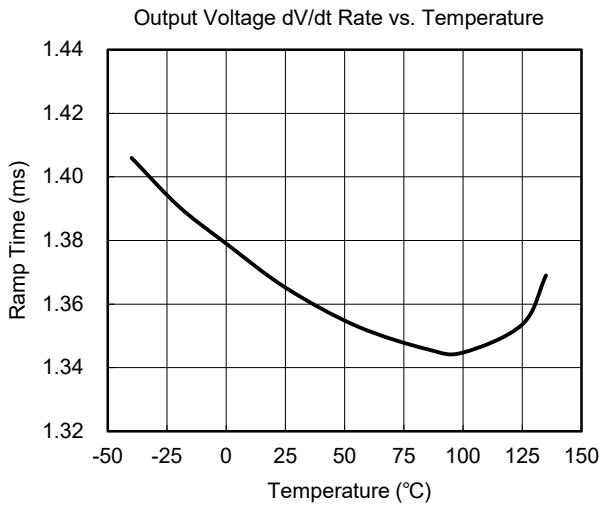
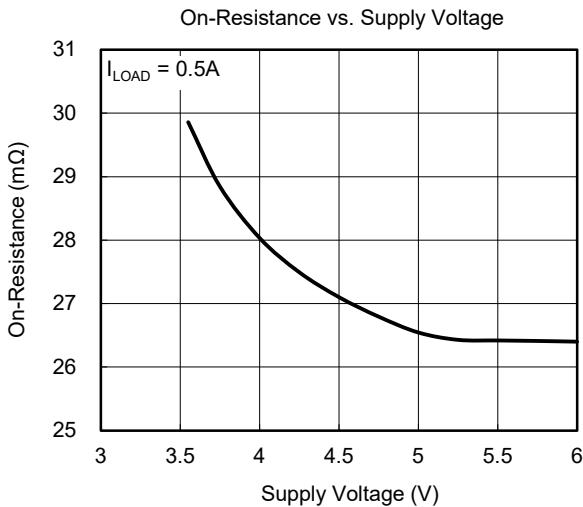
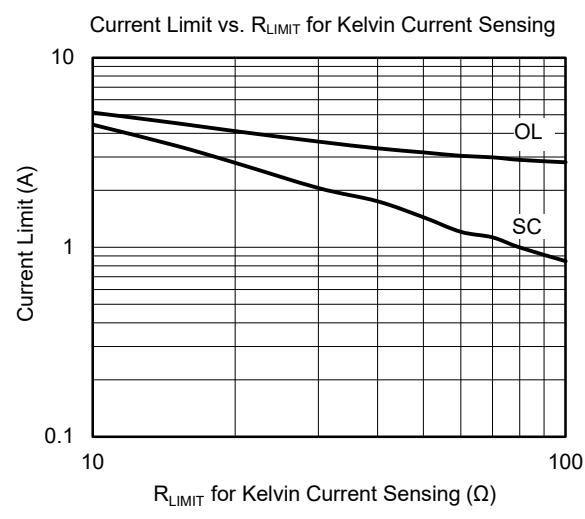
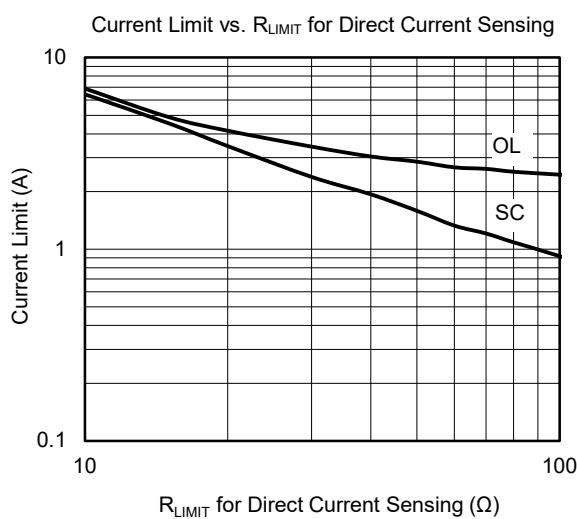
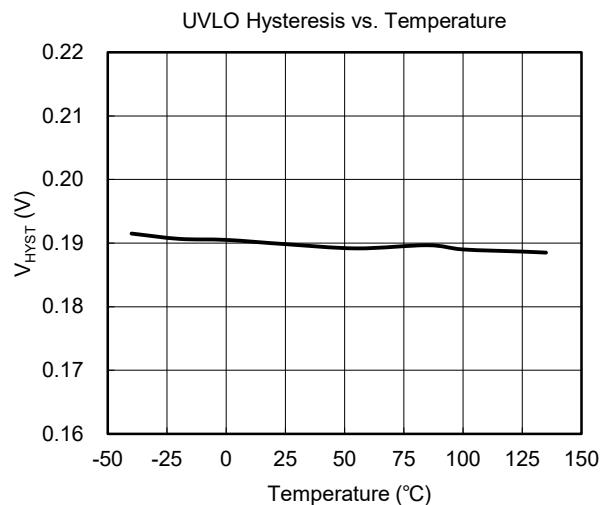
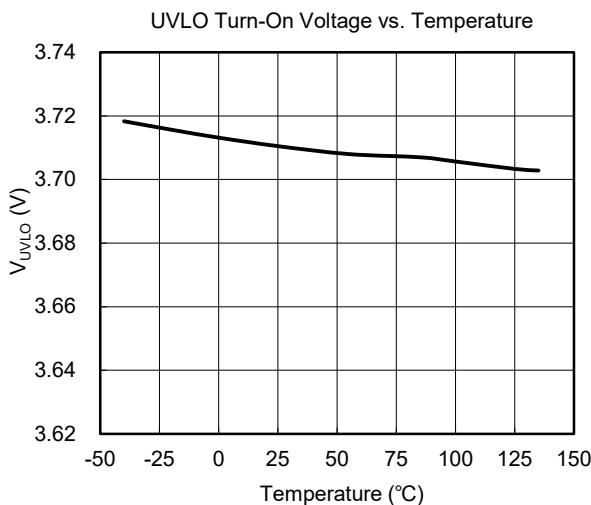
## PIN DESCRIPTION

PIN	NAME	FUNCTION
1	GND	Ground.
2	dV/dt	Internal dV/dt Circuit. Leaving this pin open will allow the device to ramp up in 1.4ms. An external capacitor between this pin and GND will set the slew rate according to the application requirements.
3	ENABLE/FAULT	Enable or Fault Pin. This pin is a 3-state, bidirectional interface. Asserting ENABLE/FAULT pin high enables the device. When the thermal shutdown occurs, the device sinks current from ENABLE/FAULT, and pulls the pin low to alert the host (this pin is used as output port).
4	$I_{LIMIT}$	Current Limit Pin. This pin is used to set the overload and short-circuit current limit levels by placing a resistor.
5	NC	No Connection.
6 - 10	SOURCE	Power Output Pins.
Exposed Pad	$V_{cc}$	Power Input Pin. Power input and supply voltage of the device.

**ELECTRICAL CHARACTERISTICS**(T<sub>J</sub> = +25°C, V<sub>CC</sub> = 5V and dV/dt pin is open, unless otherwise noted.)

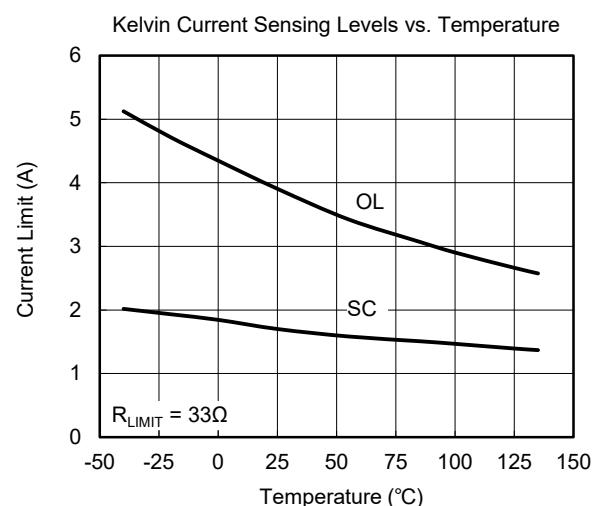
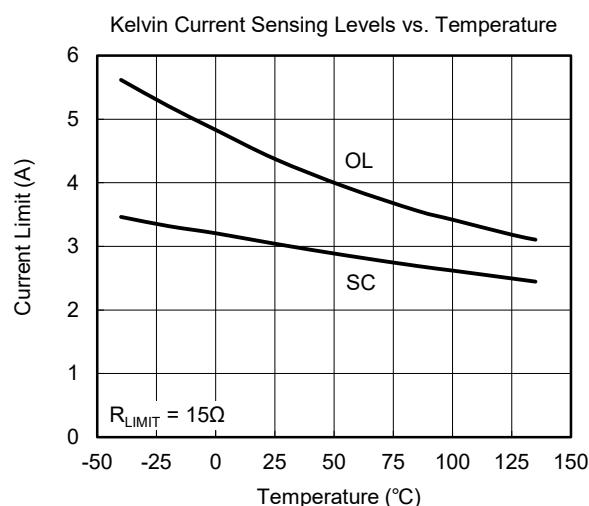
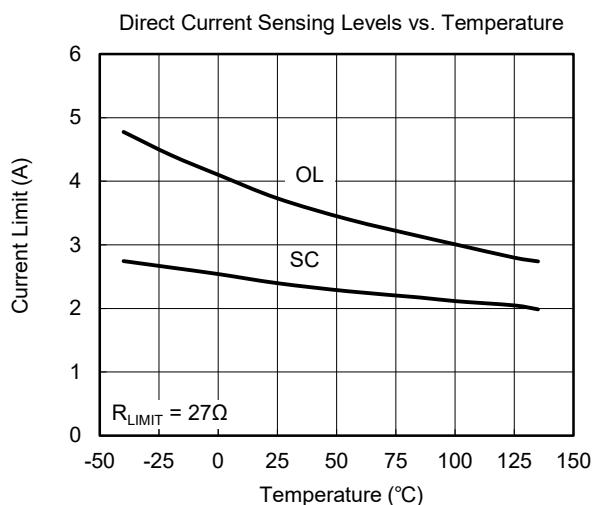
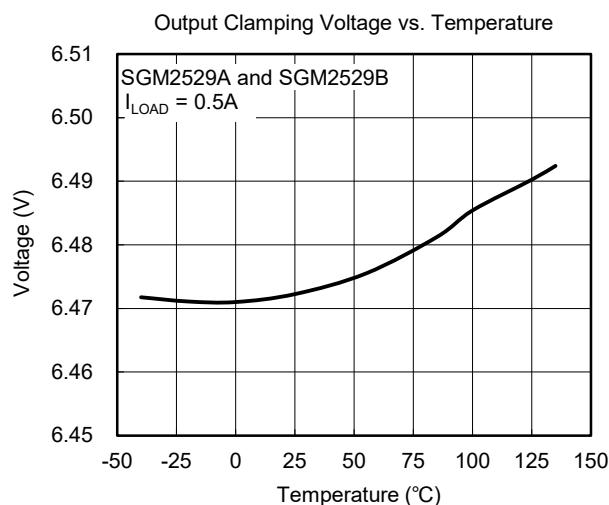
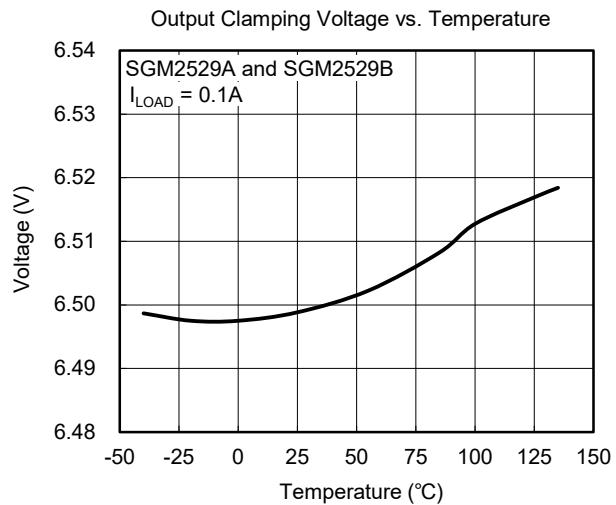
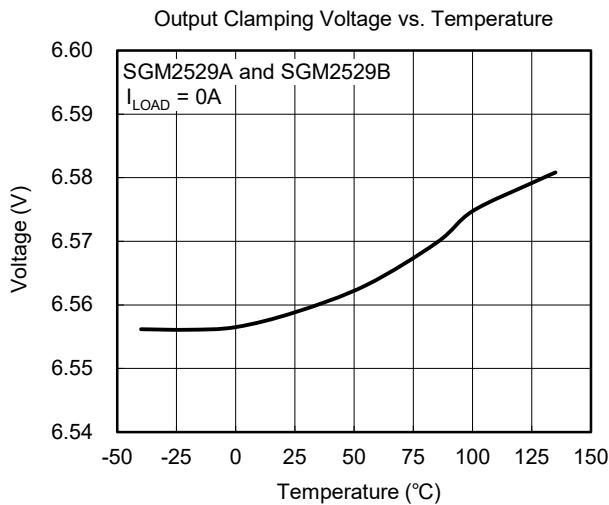
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>Power FET</b>						
Delay Time	t <sub>DLY</sub>	Enabling of chip to I <sub>D</sub> = 100mA with 1A resistive load		352		μs
Kelvin On-Resistance	R <sub>DS(ON)</sub>	T <sub>J</sub> = +25°C	21	26	31	mΩ
		T <sub>J</sub> = +135°C		40		
Off-State Output Voltage	V <sub>OFF</sub>	V <sub>CC</sub> = 10V, V <sub>GS</sub> = 0V, R <sub>L</sub> = ∞		20	200	mV
Continuous Current	I <sub>D</sub>			5		A
<b>Thermal Latch</b>						
Shutdown Temperature	T <sub>SD</sub>			158		°C
Thermal Hysteresis	T <sub>HYST</sub>	Decrease in die temperature for turn-on; does not apply to latch-off options.		22		°C
<b>Under/Over-Voltage Protection</b>						
Output Clamping Voltage	V <sub>CLAMP</sub>	Over-voltage protection, V <sub>CC</sub> = 10V	6.2	6.55	6.9	V
Under-Voltage Lockout	V <sub>UVLO</sub>	Turn on, voltage going high	3.5	3.7	3.9	V
UVLO Hysteresis	V <sub>HYST</sub>			0.2		V
<b>Current Limit</b>						
Kelvin Short-Circuit Current Limit	I <sub>LIM-SC</sub>	R <sub>LIMIT</sub> = 77Ω	0.5	0.95	1.4	A
Kelvin Overload Current Limit	I <sub>LIM-OL</sub>	R <sub>LIMIT</sub> = 77Ω		3.3		A
<b>dV/dt Circuit</b>						
Output Voltage Ramp Time	t <sub>SLEW</sub>	Enable to V <sub>OUT</sub> = 4.7V	0.9	1.4	1.9	ms
Maximum Capacitor Voltage	V <sub>MAX</sub>				5.3	V
<b>ENABLE/FAULT Pin</b>						
Logic Level Low	V <sub>IN-LOW</sub>	Output disabled	0.43	0.53	0.63	V
Logic Level Mid	V <sub>IN-MID</sub>	Thermal fault, output disabled	1.32	1.42	1.52	V
Logic Level High	V <sub>IN-HIGH</sub>	Output enabled	1.94	2.04	2.14	V
High State Maximum Voltage	V <sub>IN-MAX</sub>		4.9	5.1	5.3	V
Logic Low Sink Current	I <sub>IN-LOW</sub>	V <sub>ENABLE</sub> = 0V		-13	-19	μA
<b>Power Supply</b>						
Quiescent Current	I <sub>Q</sub>	Operating		102	130	μA
		Shutdown		47		

## TYPICAL PERFORMANCE CHARACTERISTICS

 $T_J = +25^\circ\text{C}$ , unless otherwise noted.

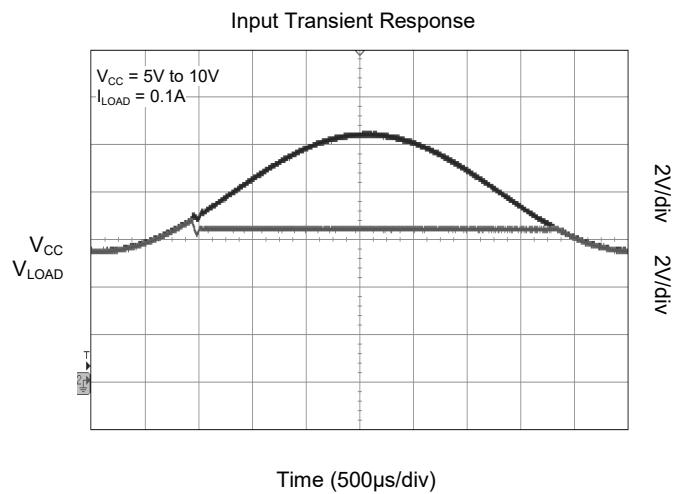
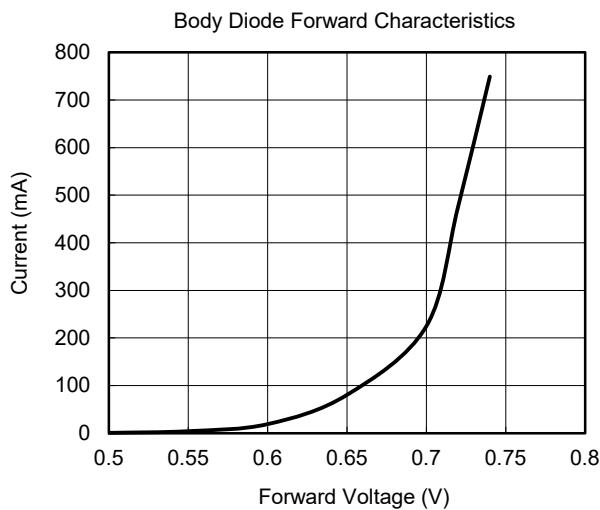
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**

$T_J = +25^\circ\text{C}$ , unless otherwise noted.



**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**

$T_J = +25^\circ\text{C}$ , unless otherwise noted.



## TYPICAL APPLICATION CIRCUITS

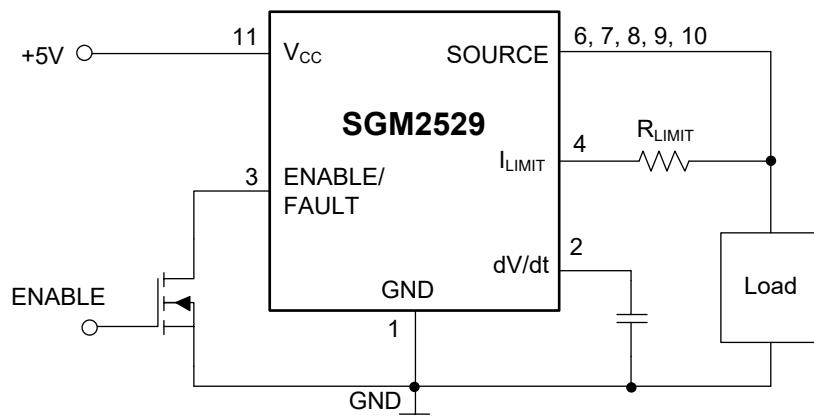


Figure 1. Application Circuit with Direct Current Sensing

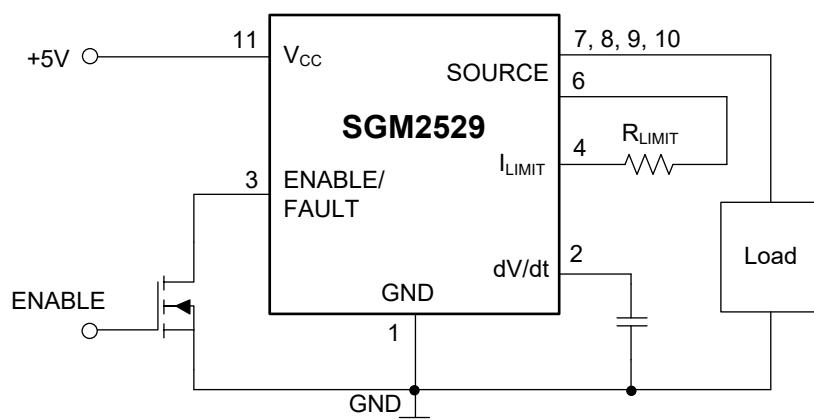


Figure 2. Application Circuit with Kelvin Current Sensing

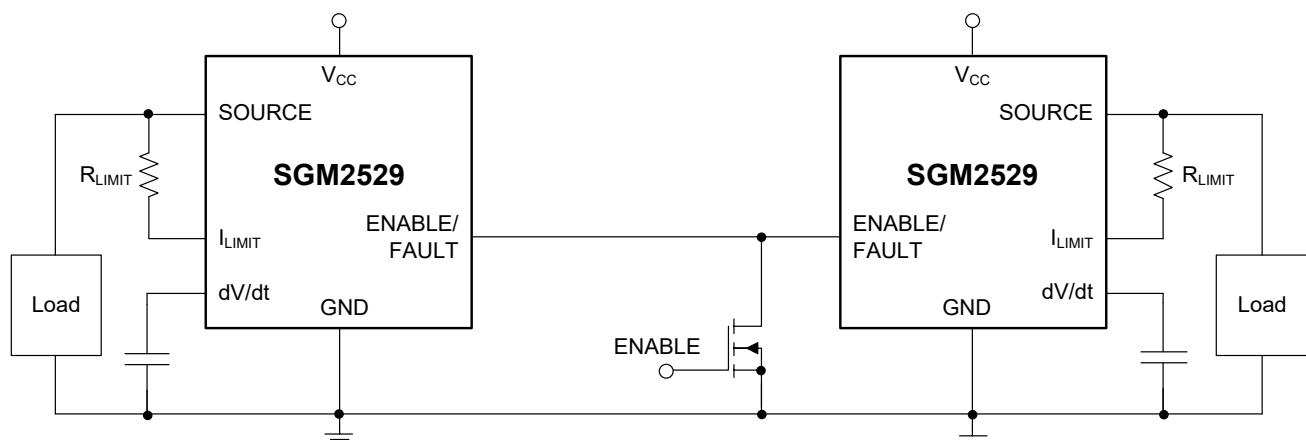
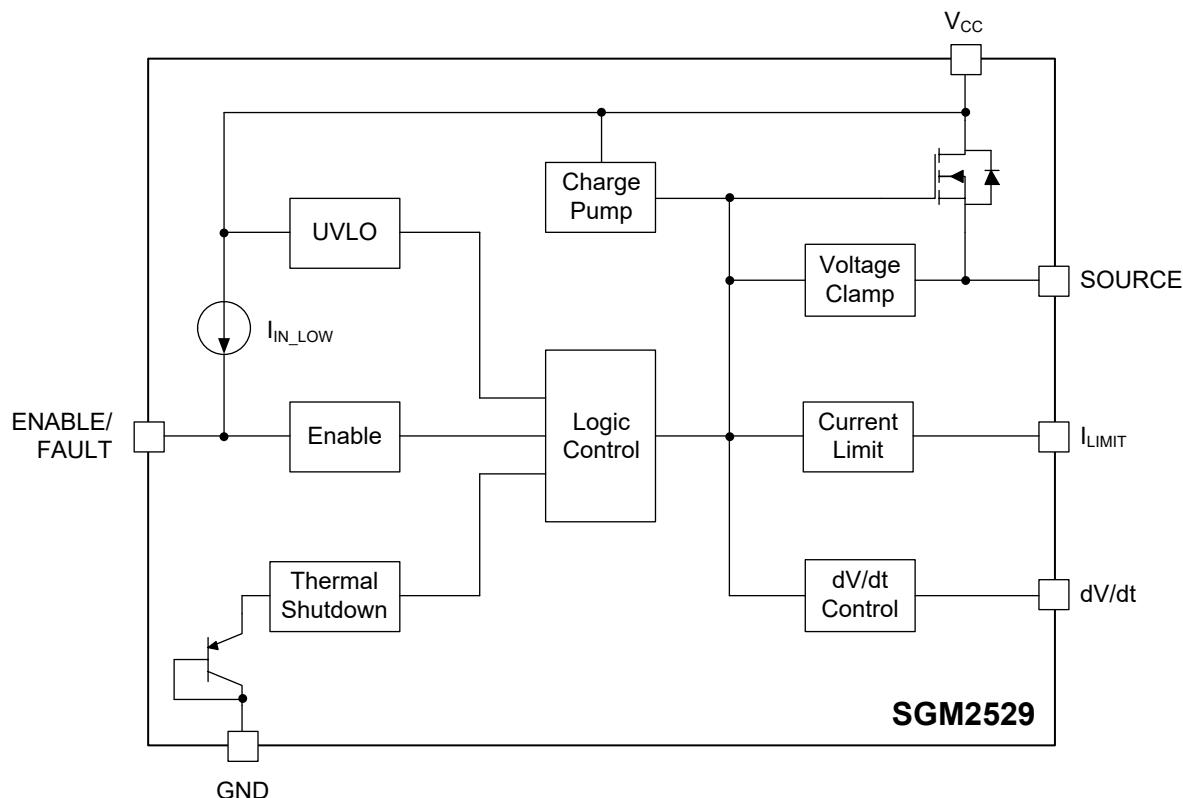


Figure 3. Common Thermal Shutdown

## FUNCTIONAL BLOCK DIAGRAM



NOTE 1: SGM2529A and SGM2529B versions.

Figure 4. Block Diagram

## REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Original (OCTOMBER 2020) to REV.A

Page

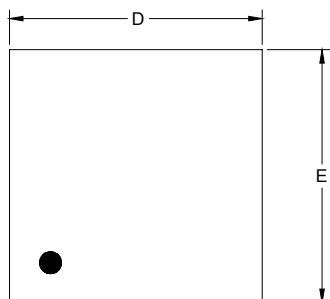
Changed from product preview to production data.....All

## PACKAGE INFORMATION

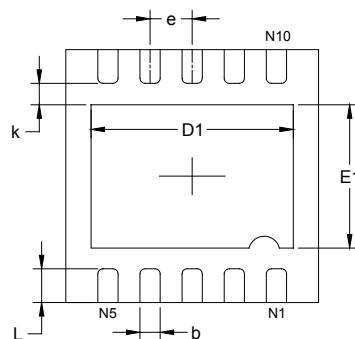
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### PACKAGE OUTLINE DIMENSIONS

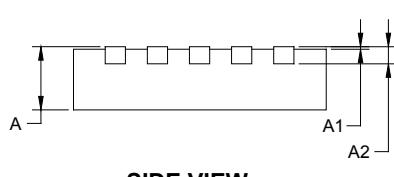
**TDFN-3x3-10L**



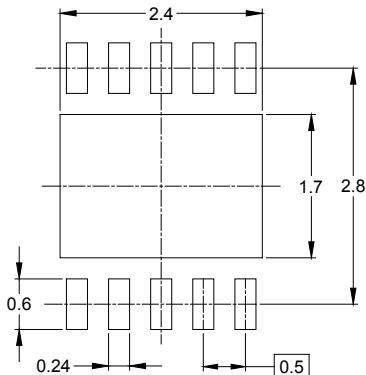
TOP VIEW



BOTTOM VIEW



SIDE VIEW



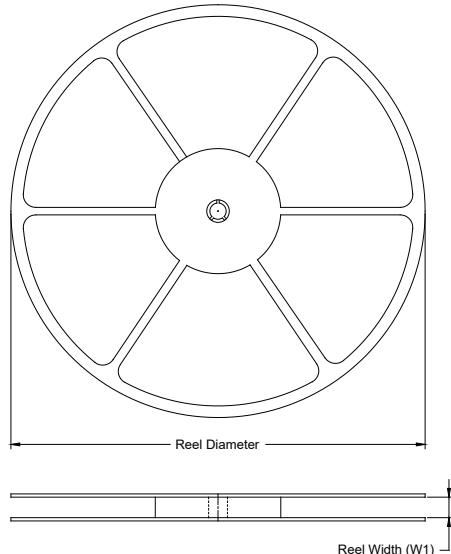
RECOMMENDED LAND PATTERN (Unit: mm)

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203 REF		0.008 REF	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.103
E	2.900	3.100	0.114	0.122
E1	1.500	1.800	0.059	0.071
k	0.200 MIN		0.008 MIN	
b	0.180	0.300	0.007	0.012
e	0.500 TYP		0.020 TYP	
L	0.300	0.500	0.012	0.020

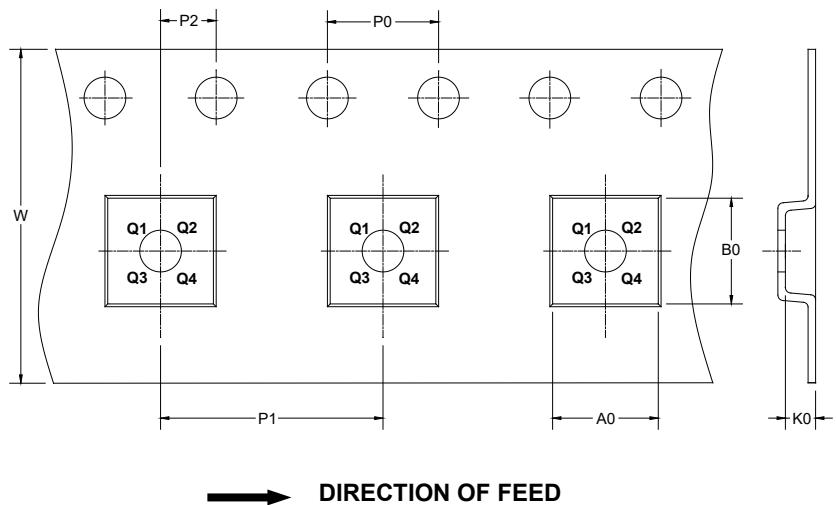
# PACKAGE INFORMATION

## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



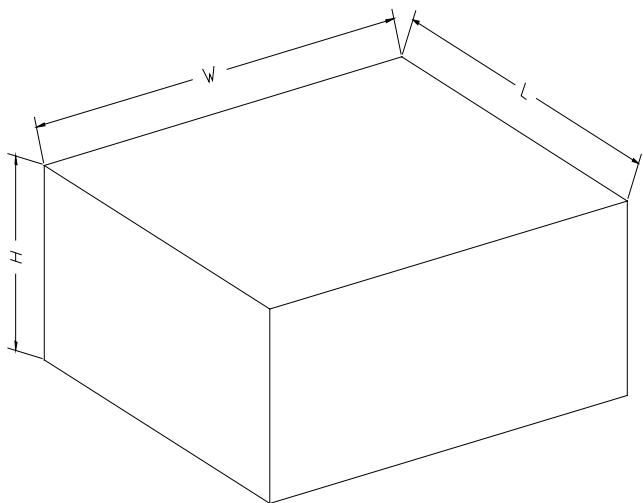
NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TDFN-3x3-10L	13"	12.4	3.35	3.35	1.13	4.0	8.0	2.0	12.0	Q1

## PACKAGE INFORMATION

### CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5

00002